Vishay Semiconductors



Component Construction

Photodetector and infrared emitter components are available in plastic or metal packages.

Plastic devices mostly include a lens to improve radiant sensitivity or radiant intensity. Detector chips are mounted on flat leadframe surfaces while leadframes for emitters have a silver plated reflector performing higher radiant intensity.

Devices in metal packages are hermetically sealed, are released for extended operating temperature range and have small optical and mechanical tolerances.







